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# PMP8650\_RevA

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C101	3.3nF	Capacitor, Ceramic,	0603	STD	STD
1	C102	680pF	Capacitor, Ceramic,	0603	STD	STD
1	C103	DNP	Capacitor, Ceramic,	0603	STD	STD
1	C104	47p	Capacitor, Ceramic,	0603	STD	STD
1	C105	330pF	Capacitor, Ceramic,	0603	STD	STD
1	C106	1000pF	Capacitor, Ceramic,	0603	STD	STD
1	C107	1500pF	Capacitor, Ceramic Disk, 220V		ECKANAxMB	Panasonic
1	C108	33uF	Capacitor, Aluminum, SM, vvV,	5 x 5.8 mm	EEFK1E220R	Panasonic
1	C109	0.1uF	Capacitor, Ceramic,	0603	STD	STD
3	C110 C114 C120	DNP	Capacitor, Ceramic Chip, 16V, ±10%	1206	STD	STD
1	C111	330uF	Capacitor, Aluminum, SMT, 6.3V, [temp], [tol]	7343(D)	6TPE330ML	Sanyo
1	C112	22uF	Capacitor, Ceramic Chip, 6.3V, ±10%	1210	Std	STD
1	C113	100pF	Capacitor, Ceramic, 630V, COG, 10%	1206		TDK
4	C115-116	22uF	Capacitor, Ceramic Chip, 25V, ±10%	1210	Std	STD
2	C117 C119	0.033uF	Capacitor, Leaded, 305 VAC, ±yy%	0.157 x 0.512	B32922C3 xxx	Epcos
1	C118	10uF	Capacitor, Electrolytic 20±%	12.5x20 mm	EKXG401ELL100N	Nippon Chem
1	C200	2.2uF	Capacitor, Ceramic Chip, xxV, ±10%	0805	STD	STD
1	C201	4.7nF	Capacitor, Ceramic,	0603	STD	STD
3	D101 D105 D108	15V	Diode, Zener, xx-V, yy-mA, zz-mW, q%	SOT23	MMBZ5245BLT1G	
1	D102	BAS19	Diode, Switching	SOT23	BAS19	Zetex
1	D103	MBRA140A	Diode, Rectifier, xx-mA, yy-V	SMA	STD	STD
1	D104	US1J	Diode, Schottky, xx-A, xx-V	SMB	STD	STD
1	D106	RH04	Bridge Rectifier, xxxV, 0.5A, Glass Passivated, Fast R	MiniDIP	RH06-T	Diodes
2	D107 D109	MURA120	Diode, Rectifier, xx-mA, yy-V	SMA	STD	STD
1	F101	0.5A	Fuse, TR5 Series			Wickmann
3	J101-103	TBD	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25		OST
1	L101	39mH	Inductor, Coupled ±30%	7.5x15 mm	744821039	WE

1	Q101	STP16N65M5	MOSFET, N-ch, xx-V, yy-mA, zz-milliOhms	TO220	STP16N65M5	Vishay
1	Q102	BSP135	MOSFET, Nch, 600V, 0.4 A, 8.5 Ohm	SOT-223	STN1HNK60	ST
1	R101	6.49k	Resistor, Chip, 1/16W, 0.1%	0603	STD	STD
2	R102 R201	2k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R103	3.74k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R104	1.8	Resistor, Chip, 1/16W, x%	0805	Std	Std
1	R105	1k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R106	10k	Resistor, Chip, 1/16W, 0.1%	0603	STD	STD
1	R107	DNP	Resistor, Chip, 1/16W, x%	0603	Std	Std
4	R109-110 R118 R120	0	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R111	15k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R112	49.9	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R113	3.4M	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R114	10	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R115	DNP	Resistor, Metal Film, 1/4 watt, ± 5%	2512	Std	STD
1	R116	100k	Resistor, Metal Film, 1/4 watt, ± 5%	2512	Std	STD
1	R117	10k	Resistor, Metal Film, 1/4 watt, ± 5%	1206	Std	Std
1	R119	100	Resistor, Metal Film, 1/4 watt, ± 5%	1206	Std	Std
1	T1	2.2 mH	Transformer, ±10%	0.665 x 0.740	750811831	
7	TP101 TP103-104 TP106 TP109-110 TP112	TBD	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch		Keystone
3	TP105 TP107 TP111	TBD	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch		Keystone
1	TP108	TBD	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100	5000	Keystone
1	U101	TLV431B	IC, Low-Voltage Adjustable Shunt Regulator	SOT23-3	TLV431CDBZx	TI
1	U102	FOD817A	IC, Optocoupler, xx-V, yy% CTR	SMT-4PDIP	FOD817xx	Fairchild
1	U103	LM5023MM	IC, AC-DC Quasi-Resonant Current Mode PWM Cont	MSOP	LM5023MM	National Ser

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
  2. These assemblies must be clean and free from flux and all contaminants.  
Use of no clean flux is not acceptable.
  3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.

4. Ref designators marked with an asterisk (\*\*\*) cannot be substituted.  
All other components can be substituted with equivalent MFG's components.

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